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(71) Applicant:

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(54) SEMICONDUCTOR DEVICE AND MANUFACTURE COPYRIGHT: (C)2000,JPO **THEREOF**

(57) Abstract:

PROBLEM TO BE SOLVED: provide semiconductor device together manufacturing method wherein collector resistance is reduced with no raised impurity concentration in the collector region.

SOLUTION: A first conductivity collector region 5 formed on the surface layer of semiconductor substrates 1 and 2, second conductivity base regions 7 and 8 formed at a part of a collector region surface layer, first conductivity emitter region 10 formed at a part of a base region surface layer, and first conductivity collector tap region 9 which is formed on a collector region surface layer with a specified gap from the base region, are provided. Here, the collector tap region is formed lower than the emitter region surface and base region surface.

